

# 3.3 V/5 V ECL 6-Bit Differential Register with Master Reset



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## MC10EP451, MC100EP451

### Description

The MC10/100EP451 is a 6-bit fully differential register with common clock and single-ended Master Reset (MR). It is ideal for very high frequency applications where a registered data path is necessary.

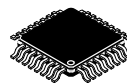
All inputs have a 75 kΩ pull-down resistor internally. Differential inputs have an override clamp. Unused differential register inputs can be left open and will default LOW. When the differential inputs are forced to  $< V_{EE} + 1.2$  V, the clamp will override and force the output to a default state. When in the default state, and since the flip-flop is edge triggered, the output reaches a determined, but not predicted, valid state.

The positive transition of CLK (pin 4) will latch the registers. Master Reset (MR) HIGH will asynchronously reset all registers forcing Q outputs to go LOW.

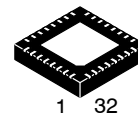
The 100 Series contains temperature compensation.

### Features

- 450 ps Typical Propagation Delay
- Maximum Frequency > 3.0 GHz Typical
- Asynchronous Master Reset
- 20 ps Skew Within Device, 35 ps Skew Device-To-Device
- PECL Mode Operating Range:  $V_{CC} = 3.0$  V to 5.5 V  
With  $V_{EE} = 0$  V
- NECL Mode Operating Range:  $V_{CC} = 0$  V  
With  $V_{EE} = -3.0$  V to  $-5.5$  V
- Open Input Default State
- Safety Clamp on Inputs
- These Devices are Pb-Free and are RoHS Compliant

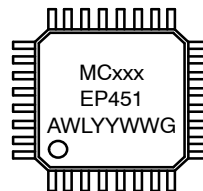


LQFP-32  
FA SUFFIX  
CASE 561AB



QFN32  
MN SUFFIX  
CASE 488AM

### MARKING DIAGRAMS\*



- xxx = 10 or 100
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

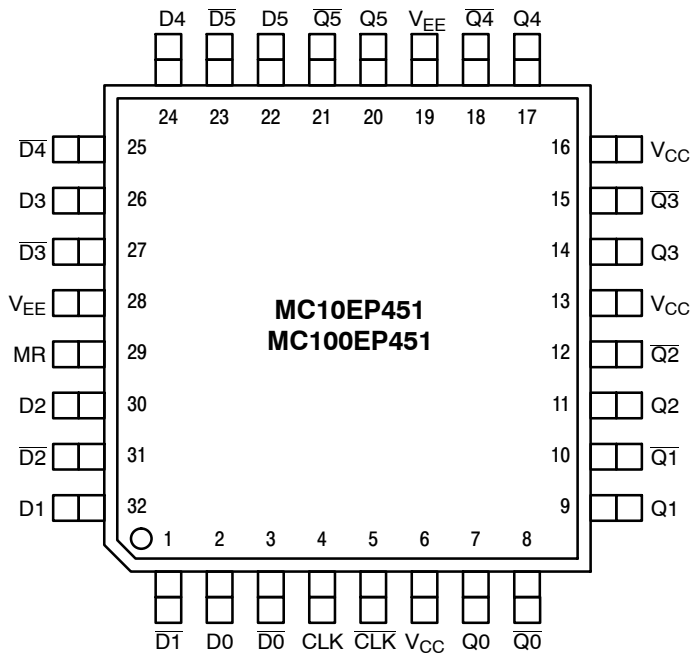
\*For additional marking information, refer to Application Note [AND8002/D](#).

### ORDERING INFORMATION

Device	Package	Shipping†
MC10EP451FAG	LQFP-32 (Pb-Free)	250 Units / Tube
MC100EP451FAG	LQFP-32 (Pb-Free)	250 Units / Tube
MC100EP451FAR2G	LQFP-32 (Pb-Free)	2000 / Tape & Reel
MC100EP451MNG	QFN-32 (Pb-Free)	72 Units / Tube
MC100EP451MNR4G	QFN-32 (Pb-Free)	1000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MC10EP451, MC100EP451



Warning: All  $V_{CC}$  and  $V_{EE}$  pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. LQFP-32 Pinout (Top View)

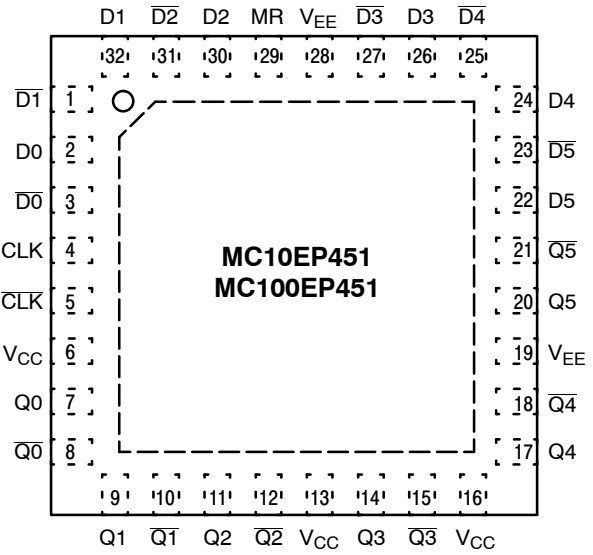


Figure 2. QFN-32 Pinout (Top View)

Table 1. PIN DESCRIPTION

PIN	FUNCTION
D [0:5]*, $\bar{D}$ [0:5]*	ECL Differential Data Inputs
MR*	ECL Master Reset Input
CLK*, $\bar{CLK}$ *	ECL Differential Clock Inputs
Q [0:5], $\bar{Q}$ [0:5]	ECL Differential Data Outputs
$V_{CC}$	Positive Supply
$V_{EE}$	Negative Supply
EP for QFN-32, only	The Exposed Pad (EP) on the QFN-32 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is electrically connected to $V_{EE}$ .

\* Pins will default LOW when left open.

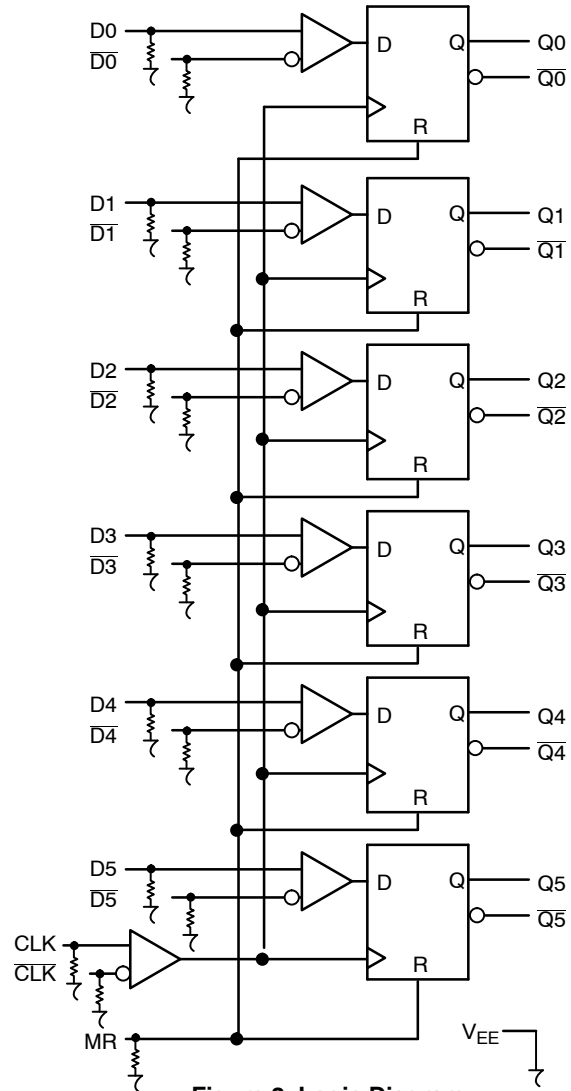


Figure 3. Logic Diagram

# MC10EP451, MC100EP451

**Table 2. ATTRIBUTES**

Characteristics	Value
Internal Input Pulldown Resistor	75 k $\Omega$
Internal Input Pullup Resistor	N/A
ESD Protection Human Body Model Machine Model Charged Device Model	> 2 kV > 200 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Pb-Free Pkg
LQFP-32 QFN-32	Level 2 Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	919 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note [AND8003/D](#).

**Table 3. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	PECL Mode Power Supply	V <sub>EE</sub> = 0 V		6	V
V <sub>EE</sub>	NECL Mode Power Supply	V <sub>CC</sub> = 0 V		-6	V
V <sub>I</sub>	PECL Mode Input Voltage NECL Mode Input Voltage	V <sub>EE</sub> = 0 V V <sub>CC</sub> = 0 V	V <sub>I</sub> $\leq$ V <sub>CC</sub> V <sub>I</sub> $\geq$ V <sub>EE</sub>	6 -6	V V
I <sub>out</sub>	Output Current	Continuous Surge		50 100	mA mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	$^{\circ}$ C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	$^{\circ}$ C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	LQFP-32 LQFP-32	80 55	$^{\circ}$ C/W $^{\circ}$ C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	LQFP-32	12 to 17	$^{\circ}$ C/W
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	QFN-32 QFN-32	31 27	$^{\circ}$ C/W $^{\circ}$ C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	2S2P	QFN-32	12	$^{\circ}$ C/W
T <sub>sol</sub>	Wave Solder Pb-Free			265	$^{\circ}$ C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# MC10EP451, MC100EP451

**Table 4. 10EP DC CHARACTERISTICS, PECL  $V_{CC} = 3.3\text{ V}$ ,  $V_{EE} = 0\text{ V}$  (Note 2)**

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current	80	95	125	80	95	125	80	95	125	mA
$V_{OH}$	Output HIGH Voltage (Note 3)	2165	2290	2415	2230	2355	2480	2290	2415	2540	mV
$V_{OL}$	Output LOW Voltage (Note 3)	1365	1490	1615	1430	1555	1680	1470	1615	1740	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended)	2090		2415	2155		2480	2215		2540	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	1365		1690	1430		1755	1490		1815	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	2.0		3.3	2.0		3.3	2.0		3.3	V
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			$\mu\text{A}$

**Table 5. 10EP DC CHARACTERISTICS, PECL  $V_{CC} = 5.0\text{ V}$ ,  $V_{EE} = 0\text{ V}$  (Note 5)**

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current	80	95	125	80	95	125	80	95	125	mA
$V_{OH}$	Output HIGH Voltage (Note 3)	3865	3990	4115	3930	4055	4180	3990	4115	4240	mV
$V_{OL}$	Output LOW Voltage (Note 3)	3065	3190	3315	3130	3255	3380	3170	3315	3440	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended)	3790		4115	3855		4180	3915		4240	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	3065		3390	3130		3455	3190		3515	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	2.0		5.0	2.0		5.0	2.0		5.0	V
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			$\mu\text{A}$

**Table 6. 10EP DC CHARACTERISTICS, NECL  $V_{CC} = 0\text{ V}$ ,  $V_{EE} = -5.5\text{ V}$  to  $-3.0\text{ V}$  (Note 6)**

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current	80	95	125	80	95	125	80	95	125	mA
$V_{OH}$	Output HIGH Voltage (Note 3)	-1135	-1010	-885	-1070	-945	-820	-1010	-885	-760	mV
$V_{OL}$	Output LOW Voltage (Note 3)	-1935	-1810	-1685	-1870	-1745	-1620	-1830	-1685	-1560	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended)	-1210		-885	-1145		-820	-1085		-760	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	-1935		-1610	-1870		-1545	-1810		-1485	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	$V_{EE}+2.0$		0.0	$V_{EE}+2.0$		0.0	$V_{EE}+2.0$		0.0	V
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

2. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.3 V to -2.2 V.
3. All loading with 50  $\Omega$  to  $V_{CC} - 2.0\text{ V}$ .
4.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ .  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.
5. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +2.0 V to -0.5 V.
6. Input and output parameters vary 1:1 with  $V_{CC}$ .

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**Table 7. 100EP DC CHARACTERISTICS, PECL**  $V_{CC} = 3.3\text{ V}$ ,  $V_{EE} = 0\text{ V}$  (Note 7)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current	85	105	135	85	105	135	85	105	135	mA
$V_{OH}$	Output HIGH Voltage (Note 8)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
$V_{OL}$	Output LOW Voltage (Note 8)	1305	1480	1605	1305	1480	1605	1305	1480	1605	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended)	2075		2420	2075		2420	2075		2420	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	1305		1675	1305		1675	1305		1675	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 9)	2.0		3.3	2.0		3.3	2.0		3.3	V
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfp/m.

7. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.3 V to -2.2 V.

8. All loading with 50  $\Omega$  to  $V_{CC} - 2.0\text{ V}$ .

9.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ ,  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.

**Table 8. 100EP DC CHARACTERISTICS, PECL**  $V_{CC} = 5.0\text{ V}$ ,  $V_{EE} = 0\text{ V}$  (Note 10)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current	85	105	135	85	105	135	85	105	135	mA
$V_{OH}$	Output HIGH Voltage (Note 11)	3855	3980	4105	3855	3980	4105	3855	3980	4105	mV
$V_{OL}$	Output LOW Voltage (Note 11)	3005	3180	3305	3005	3180	3305	3005	3180	3305	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended)	3775		4120	3775		4120	3775		4120	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	3005		3375	3005		3375	3005		3375	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 12)	2.0		5.0	2.0		5.0	2.0		5.0	V
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfp/m.

10. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +2.0 V to -0.5 V.

11. All loading with 50  $\Omega$  to  $V_{CC} - 2.0\text{ V}$ .

12.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ ,  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.

# MC10EP451, MC100EP451

**Table 9. 100EP DC CHARACTERISTICS, NECL**  $V_{CC} = 0\text{ V}$ ,  $V_{EE} = -5.5\text{ V to } -3.0\text{ V}$  (Note 13)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current	85	105	135	85	105	135	85	105	135	mA
$V_{OH}$	Output HIGH Voltage (Note 14)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
$V_{OL}$	Output LOW Voltage (Note 14)	-1995	-1820	-1695	-1995	-1820	-1695	-1995	-1820	-1695	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended)	-1225		-880	-1225		-880	-1225		-880	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	-1995		-1625	-1995		-1625	-1995		-1625	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 15)	$V_{EE}+2.0$		0.0	$V_{EE}+2.0$		0.0	$V_{EE}+2.0$		0.0	V
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

13. Input and output parameters vary 1:1 with  $V_{CC}$ .

14. All loading with  $50\ \Omega$  to  $V_{CC} - 2.0\text{ V}$ .

15.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ ,  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.

**Table 10. AC CHARACTERISTICS**  $V_{CC} = 0\text{ V}$ ;  $V_{EE} = -3.0\text{ V to } -5.5\text{ V}$  or  $V_{CC} = 3.0\text{ V to } 5.5\text{ V}$ ;  $V_{EE} = 0\text{ V}$  (Note 16)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OUTpp}$	Output Voltage Amplitude @ 3 GHz (Figure 4) (Note 17)	540	670		520	650		450	580		mV
$t_{PLH}$ , $t_{PHL}$	Propagation Delay to Output Differential CLK to Q, $\bar{Q}$ MR to Q, $\bar{Q}$	330 430	430 530	530 630	350 450	450 550	550 650	390 490	490 590	590 690	ps
$t_{RR}$	Reset Recovery MR to CLK	240	145		250	150		260	160		ps
$t_S$ , $t_H$	Setup Time Hold Time D to CLK CLK to D	80 80	40 40		80 80	40 40		80 80	40 40		ps
$t_{PW}$	Minimum Pulse Rate MR	400			400			400			ps
$t_{SKEW}$	Within-Device Skew (Note 18) Device-To-Device Skew (Note 19)		20 35	40 100		20 35	40 100		20 35	40 100	
$t_{JITTER}$	CLOCK Random Jitter (RMS) @ $\leq 3.0\text{ GHz}$ (Figure 4)		0.2	1		0.2	1		0.2	1	ps
$t_r$ , $t_f$	Output Rise/Fall Times (20% - 80%) Q, $\bar{Q}$	100 100	150 150	250 250	110 110	160 160	260 260	130 130	180 180	280 280	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

16. Measured using a 750 mV source, 50% duty cycle clock source. All loading with  $50\ \Omega$  to  $V_{CC} - 2.0\text{ V}$ .

17.  $V_{OL}$  and  $V_{OH}$  specifications not guaranteed for  $F_{max}$  testing.

18. Skew is measured between outputs under identical transitions and conditions on any one device.

19. Device-To-Device skew for identical transitions at identical  $V_{CC}$  levels.

## MC10EP451, MC100EP451

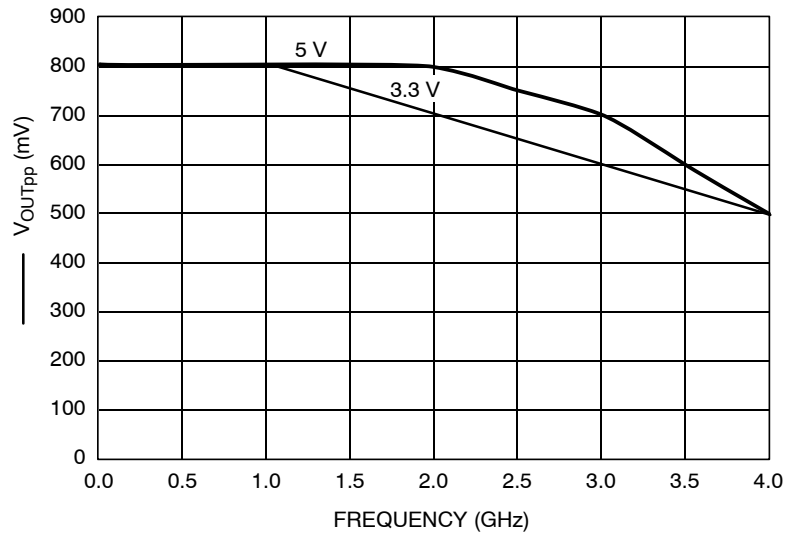


Figure 4. F<sub>max</sub> Typical

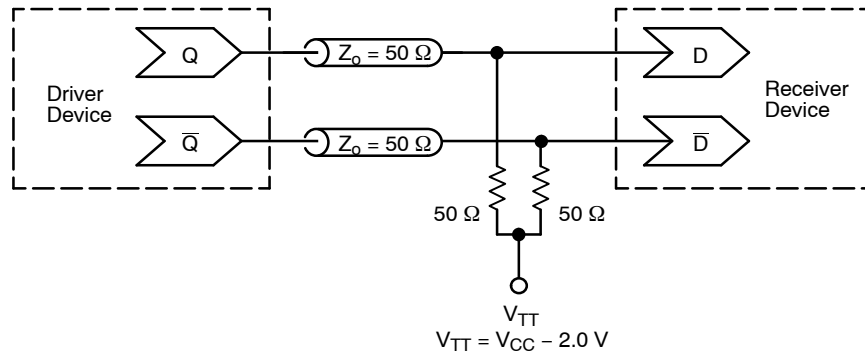


Figure 5. Typical Termination for Output Driver and Device Evaluation  
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices.)

### Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1642/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

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# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®



1 32

SCALE 2:1

QFN32 5x5, 0.5P  
CASE 488AM  
ISSUE A

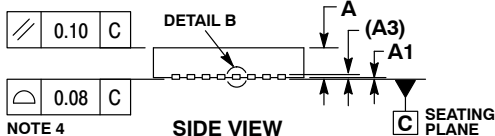
DATE 23 OCT 2013



TOP VIEW



DETAIL A  
ALTERNATE TERMINAL  
CONSTRUCTIONS



SIDE VIEW



DETAIL B  
ALTERNATE  
CONSTRUCTION

NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM THE TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

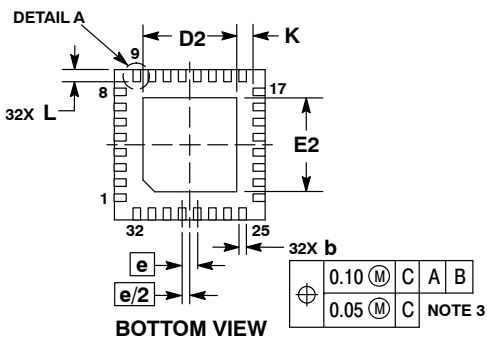
MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.18	0.30
D	5.00	BSC
D2	2.95	3.25
E	5.00	BSC
E2	2.95	3.25
e	0.50	BSC
K	0.20	---
L	0.30	0.50
L1	---	0.15

GENERIC MARKING DIAGRAM\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)  
\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON20032D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	QFN32 5x5 0.5P	PAGE 1 OF 1

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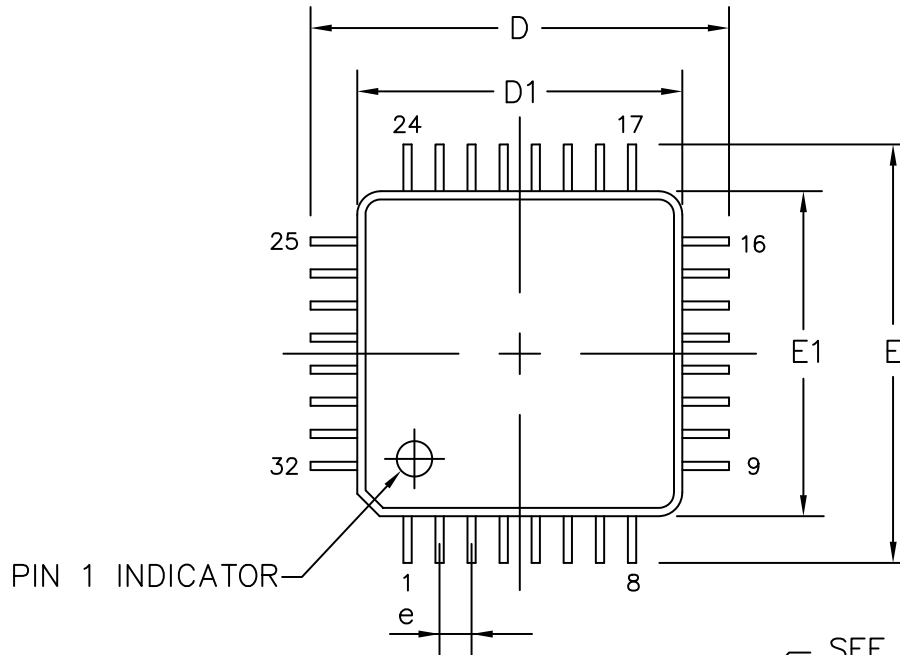
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®

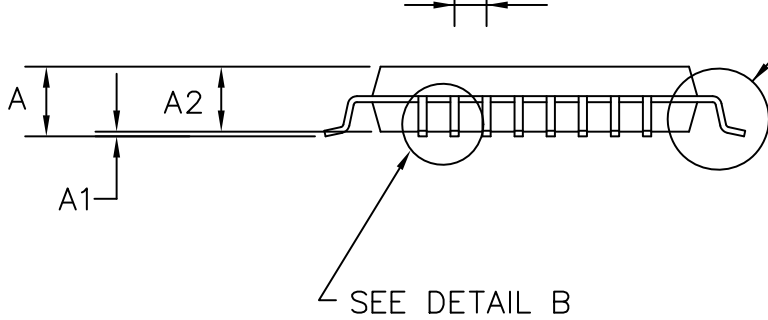


**LQFP-32, 7x7**  
**CASE 561AB-01**  
**ISSUE O**

DATE 19 JUN 2008



SYMBOL	MIN	NOM	MAX
A	—	—	1.60
A1	0.05	—	0.15
A2	1.35	1.40	1.45
B	0.30	0.37	0.45
B1	0.30	0.35	0.40
C	0.09	—	0.20
C1	0.09	—	0.16
D	9.00 BSC		
D1	7.00 BSC		
E	9.00 BSC		
E1	7.00 BSC		
e	0.80 BSC		
L	0.45	0.60	0.75
L1	1.00		
R1	0.08	—	0.20
$\alpha^\circ$	11	—	13
$\beta^\circ$	0	—	7
$\gamma^\circ$	0	—	—



ALL DIMENSIONS IN MM

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